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GaAs INTEGRATED CIRCUIT μ PG2251T6M

+25 dBm MATCHED POWER AMPLIFIER FOR Bluetooth™ Class 1

DESCRIPTION

The μ PG2251T6M is a fully matched, +25 dBm GaAs MMIC power amplifier for Bluetooth Class 1.

This device realizes high efficiency, high gain and high output power.

This device is housed in a 12-pin plastic TSQFN (\underline{T} hin \underline{S} mall \underline{Q} uad \underline{F} lat \underline{N} on-leaded) (T6M) package, and is suitable for high-density surface mounting.

FEATURES

Operating frequency : f_{opt} = 2 400 to 2 500 MHz (2 450 MHz TYP.)
 Supply voltage : V_{DD}1, 2, 3 = 2.5 to 3.5 V (3.0 V TYP.)
 Control voltage : V_{cont} = 1.5 to 2.1 V (1.8 V TYP.)

Circuit current
 IDD = 230 mA TYP. @ VDD1, 2, 3 = 3.0 V, Vcont = 1.8 V, Pout = +25 dBm
 Output power
 Pout = +25.0 dBm TYP. @ VDD1, 2, 3 = 3.0 V, Vcont = 1.8 V, Pin = -5 dBm
 Gain control range
 GCR = 70 dB TYP. @ VDD1, 2, 3 = 3.0 V, Vcont = 0 to 1.8 V, Pin = -5 dBm
 High efficiency
 PAE = 47% TYP. @ VDD1, 2, 3 = 3.0 V, Vcont = 1.8 V, Pin = -5 dBm

High-density surface mounting: 12-pin plastic TSQFN (T6M) package (2.0 × 2.0 × 0.37 mm)

APPLICATIONS

Power Amplifier for Bluetooth Class 1, ZigBeeTM etc.

ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Supplying Form
μPG2251T6M-E2	μPG2251T6M-E2-A	12-pin plastic TSQFN (T6M) (Pb-Free)	2251	Embossed tape 8 mm wide Pin 10, 11, 12 face the perforation side of the tape Qty 3 kpcs/reel

Remark: To order evaluation samples, please contact your nearby sales office.

Part number for sample order: μ PG2251T6M-A

Caution: Observe precautions when handling, because these devices are sensitive to electrostatic discharge.

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.

Pin Name

 V_{cont}

GND

GND

 P_{in}

 $V_{\text{DD}}\mathbf{1}$

 $V_{\text{DD}}2$

GND

GND

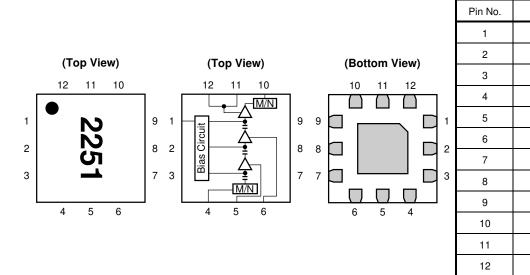
GND

Pout

 $V_{DD}3$

 $V_{\text{DD}}3$

PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM



Remark Exposed pad: GND

ABSOLUTE MAXIMUM RATINGS (TA = +25°C, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Supply Voltage	V _{DD} 1, 2, 3	6.0	V
Control Voltage	V _{cont}	3.0	V
Circuit Current	IDD	300	mA
Control Current	Icont	0.5	mA
Input Power	Pin	+10	dBm
Power Dissipation	P□	600 Note	mW
Operating Ambient Temperature	TA	-40 to +85	°C
Storage Temperature	T _{stg}	−55 to +150	°C

Note Mounted on double-sided copper-clad $50 \times 50 \times 1.6$ mm epoxy glass PWB, $T_A = +85^{\circ}C$

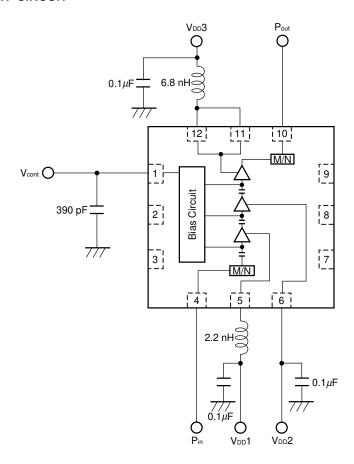
RECOMMENDED OPERATING RANGE (TA = +25°C, unless otherwise specified)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Operating Frequency	f _{opt}	2 400	2 450	2 500	MHz
Supply Voltage	V _{DD} 1, 2, 3	2.5	3.0	3.5	٧
Control Voltage	V _{cont}	1.5	1.8	2.1	٧

ELECTRICAL CHARACTERISTICS (TA = +25°C, VDD1, 2, 3 = 3.0 V, Vcont = 1.8 V, f = 2.4 to 2.5 GHz, unless otherwise specified)

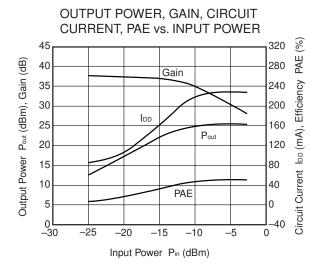
Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Circuit Current	IDD	Pin = -5 dBm	-	230	265	mA
Output Power 1	Pout1	$P_{in} = -5 \text{ dBm}$	+23	+25	-	dBm
Output Power 2	Pout2	$V_{cont} = 0 \text{ V}, P_{in} = -5 \text{ dBm}$	ı	- 4 5	-30	dBm
Gain Control Range	GCR	$V_{cont} = 0$ to 1.8 V, $P_{in} = -5$ dBm	-	70	-	dB
Efficiency	PAE	$P_{in} = -5 \text{ dBm}$	I	47	-	%
2nd Harmonics	2f0	$P_{in} = -5 \text{ dBm}$	I	-35	-	dBc
3rd Harmonics	3f0	$P_{in} = -5 \text{ dBm}$	I	-30	-	dBc
Input Return Loss	RLin	$P_{in} = -30 \text{ dBm}$	-	-5	-	dB
Output Return Loss	RLout	$P_{in} = -30 \text{ dBm}$	ı	-10	-	dB

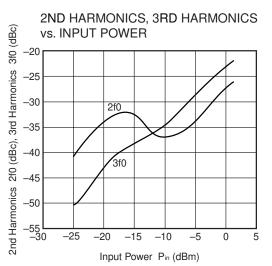
EVALUATION CIRCUIT



The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

TYPICAL CHARACTERISTICS ($T_A = +25^{\circ}C$, V_{DD1} , 2, 3 = 3.0 V, $V_{cont} = 1.8$ V, f = 2.45 GHz, unless otherwise specified)





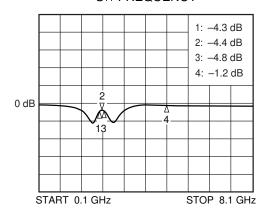
Remark The graphs indicate nominal characteristics.

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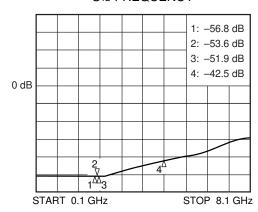
S-PARAMETERS

Condition : $T_A = +25$ °C, $V_{DD}1$, 2, 3 =3.0 V, $V_{cont} = 1.8$ V, $P_{in} = -30$ dBm

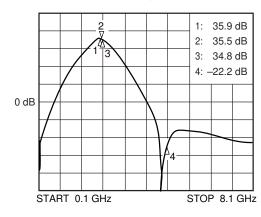
S₁₁-FREQUENCY



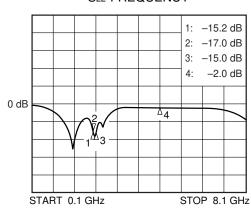
S₁₂-FREQUENCY



S21-FREQUENCY



S22-FREQUENCY



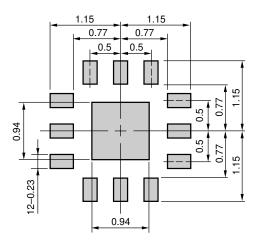
Remarks 1. The graphs indicate nominal characteristics.

2. Maker 1: 2.4 GHz, 2: 2.45 GHz, 3: 2.5 GHz, 4: 4.9 GHz

MOUNTING PAD LAYOUT DIMENSIONS

12-PIN PLASTIC TSQFN (T6M) (UNIT: mm)

MOUNTING PAD

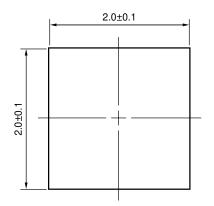


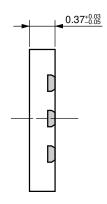
Remark The mounting pad layout in this document is for reference only.

When designing PCB, please consider workability of mounting, solder joint reliability, prevention of solder bridge and so on, in order to optimize the design.

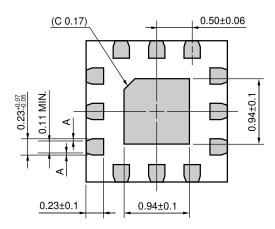
PACKAGE DIMENSIONS

12-PIN PLASTIC TSQFN (T6M) (UNIT: mm)





(Bottom View)



Remark A > 0

(): Reference value

RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions	Condition Symbol		
Infrared Reflow	Peak temperature (package surface temperature) Time at peak temperature Time at temperature of 220°C or higher Preheating time at 120 to 180°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 60 seconds or less : 120±30 seconds : 3 times : 0.2%(Wt.) or below	IR260	
Partial Heating	Peak temperature (terminal temperature) Soldering time (per side of device) Maximum chlorine content of rosin flux (% mass)	: 350°C or below : 3 seconds or less : 0.2%(Wt.) or below	HS350	

Caution Do not use different soldering methods together (except for partial heating).

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M8E0904E

Caution

GaAs Products

This product uses gallium arsenide (GaAs).

GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
- Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
- 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.